TOSHIBA Intelligent Power Module Silicon N Channel IGBT

MIG200Q101H

High Power Switching Applications Motor Control Applications

Integrates inverter power circuits & control circuits (IGBT drive units, protection units for over-current, under-voltage & over-temperature) in one package.

The electrodes are isolated from case.

High speed type IGBT : $V_{CE (sat)} = 3.5V (Max.)$

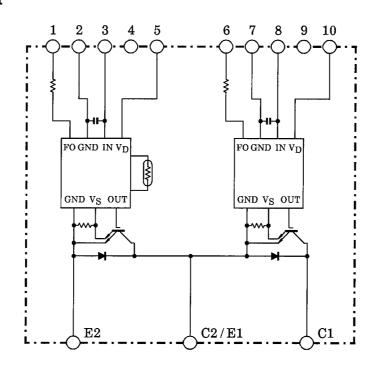
 $t_{off} = 3.8 \mu s \text{ (Max.)}$

 $t_{rr} = 0.24 \mu s$ (Max.)

Outline : TOSHIBA 2-121A1A

 Weight : 510g

Equivalent Circuit



- 1. FO (L)
- 2. GND (L)
- 3. IN (L)
- 4. Open
- 5. V_D (L) 10.V_D (H)

- 6. FO (H)
- 7. GND (H)
- 8. IN (H)

1

- 9. Open

2002-12-06

Maximum Ratings ($T_j = 25$ °C)

Stage	Characteristic	Condition	Symbol	Ratings	Unit
Inverter	Supply voltage	P-N power terminal	V _{CC}	900	V
	Collector-emitter voltage	_	V _{CES}	1200	V
	Collector current	Tc = 25°C, DC	Ic	200	Α
	Forward current	Tc = 25°C, DC	I _F	200	Α
	Collector power dissipation	Tc = 25°C	PC	1600	W
	Junction temperature	_	Tj	150	°C
Control	Control supply voltage	V _D -GND terminal	V _D	20	V
	Input voltage	IN-GND terminal	V _{IN}	20	V
	Fault output voltage	FO-GND (L) terminal	V _{FO}	20	V
	Fault output current	FO sink current	I _{FO}	14	mA
	Operating temperature	_	T _C	-20~+100	°C
Module	Storage temperature range	_	T _{stg}	-40~+125	°C
	Isolation voltage	AC 1 minute	V _{ISO}	2500	V
	Screw torque	M6	_	3	Nm

Electrical Characteristics ($T_j = 25$ °C)

a. Inverter stage

Characteristic	Symbol	Test Condition		Min	Тур.	Max	Unit
Collector cut-off current	losy	V _{CEX} = 1200V	T _j = 25°C	_	_	2	mA
Conector cut on current	I_{CEX} $V_{CEX} = 1200V$ $T_j = 1200V$	T _j = 125°C	_	_	40	IIIA	
Collector-emitter saturation voltage	V _{CE} (sat) V _C = 3V 0V	V _D = 15V, I _C = 200A	T _j = 25°C	_	2.7	3.5	V
Conector-entitler saturation voltage		T _j = 125°C	_	2.6	_	V	
Forward voltage	V _F	I _F = 200A		_	2.0	2.7	V
	t _{on}	V _{CC} = 600V, I _C = 200A		8.0	1.5	2.2	
	t _{c (on)}			_	0.5	1.0	
Switching time	t _{rr}	V _D = 15V, V _{IN} = 3V↔0V Inductive load — 0.16	0.16	0.24	μs		
	t _{off}		(Note 1)	_	3.3	3.8	
	t _{c (off)}			_	0.4	0.8	

2



b. Control Stage $(T_j = 25^{\circ}C)$

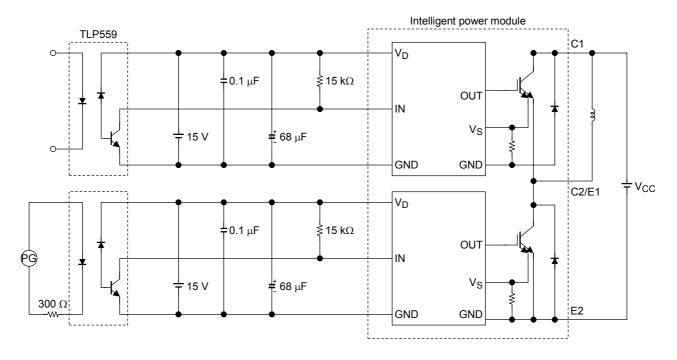
Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit
Control circuit current		I _D	V _D = 15V	_	20	30	mA
Input on signal voltage		V _{IN (on)}	V _D = 15V, I _C = 200mA	0.9	1.1	1.3	V
Fault output current	Protection	I _{FO (on)}	-V _D = 15V	8	10	12	mA
	Normal	I _{FO (off)}		_	_	1	
Over current protection trip level		ОС	V _D = 15V, T _j = 125°C	280	400	_	Α
Short circuit protection trip level		SC	V _D = 15V, T _j = 125°C	420	600	_	Α
Over current cut-off time		t _{off (OC)}	V _D = 15V	_	10	_	μs
Over temperature	Trip level	OT	Casa tamparatura	amperature 111 118	125	- °C	
protection	Reset level	OTr	Case temperature 93	100	107		
Control supply under voltage protection	Trip level	UV		11.3	12.0	12.7	V
	Reset level	UVr		11.8	12.5	13.2	
Fault output pulse width		t _{FO}	V _D = 15V	1	2	3	ms

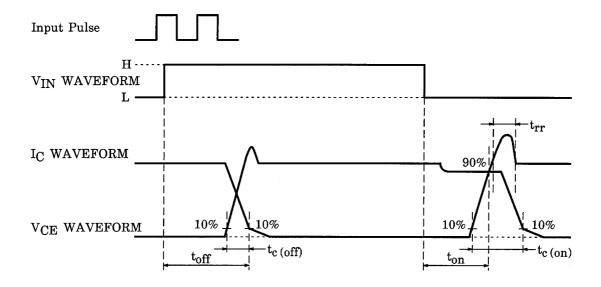
c. Thermal Resistance ($T_j = 25$ °C)

Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Junction to case thermal resistance	R _{th (j-c)}	IGBT	_	_	0.078	- °C/W
Junction to case thermal resistance		FRD	_	_	0.25	
Case to fin thermal resistance	R _{th (c-f)}	Compound is applied	_	0.05	_	°C/W

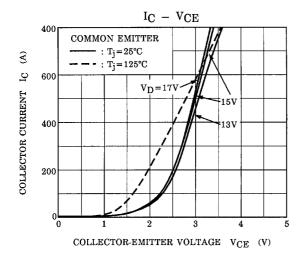
3 2002-12-06

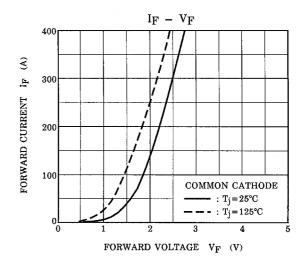
Note 1: Switching time test circuit & timing chart

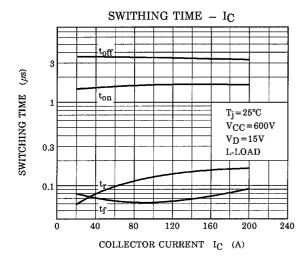


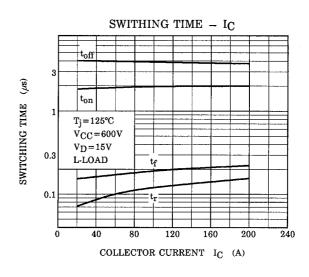


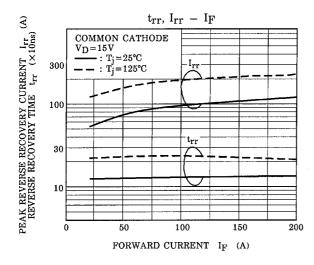
4

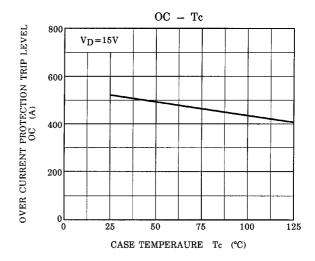




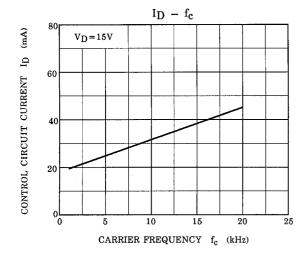


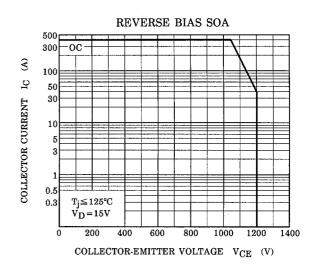


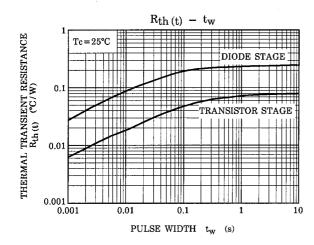




5





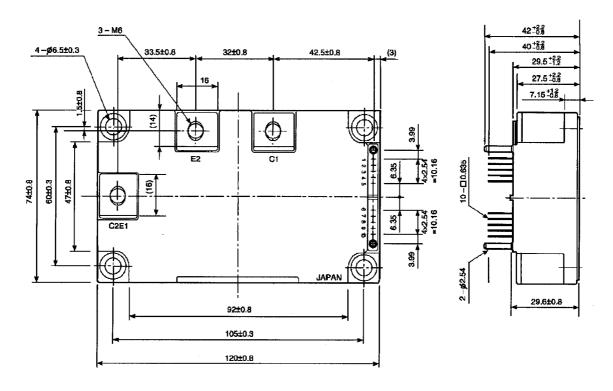


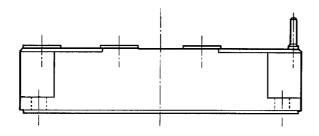
6 2002-12-06

Package Dimensions

TOSHIBA 2-121A1A

Unit: mm





- 1. FO (L)
- 2. GND (L)
- 3. IN (L)
- 4. Open
- $\begin{array}{ccc} 5. & \mathrm{V_D} & \mathrm{(L)} \\ 10. & \mathrm{V_D} & \mathrm{(H)} \end{array}$

- 6. FO (H)
- 7. GND (H)
- 8. IN (H)
- 9. Open

RESTRICTIONS ON PRODUCT USE

000707EAA

- TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property. In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability Handbook" etc..
- The TOSHIBA products listed in this document are intended for usage in general electronics applications (computer, personal equipment, office equipment, measuring equipment, industrial robotics, domestic appliances, etc.). These TOSHIBA products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, airplane or spaceship instruments, transportation instruments, traffic signal instruments, combustion control instruments, medical instruments, all types of safety devices, etc.. Unintended Usage of TOSHIBA products listed in this document shall be made at the customer's own risk.
- The information contained herein is presented only as a guide for the applications of our products. No
 responsibility is assumed by TOSHIBA CORPORATION for any infringements of intellectual property or other
 rights of the third parties which may result from its use. No license is granted by implication or otherwise under
 any intellectual property or other rights of TOSHIBA CORPORATION or others.
- The information contained herein is subject to change without notice.

This datasheet has been download from:

www.datasheetcatalog.com

Datasheets for electronics components.